

Description

P-channel Enhancement Mode Power MOSFET

Features

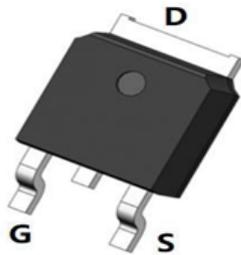
- -60V, -40A
- $R_{DS(ON)} < 28m\Omega @ V_{GS} = -10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge

Applications

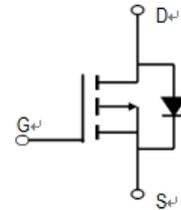
- Battery switching application
- Hard switched and high frequency circuits
- Power Management



100% UI TESTED!
100% ΔVds TESTED!



TO-252-3L



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel (pcs)	Per Carton (pcs)
OCG40P06K	OCG40P06K	TAPING	TO-252-3L	13"	2500	25000

Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	-60	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-40
		$T_C = 100^\circ\text{C}$	-24
I_{DM}	Pulsed Drain Current ⁽¹⁾	-320	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	100	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	65
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.9	$^\circ\text{C/W}$
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D =-250μA, V _{GS} =0V	-60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-60V, V _{GS} =0V	-	-	-1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.2	-1.8	-2.5	V
R _{DS(ON)}	Static Drain- Source ON- Resistance ⁽³⁾	V _{GS} =-10V, I _D =-15A	-	21.0	28.0	mΩ □
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-30V, f=1MHz	-	1568	-	pF
C _{oss}	Output Capacitance		-	291	-	pF
C _{rss}	Reverse Transfer Capacitance		-	21	-	pF
Q _g	Total Gate Charge	V _{GS} =0to-10V V _{DS} =-30V, I _D =-3A	-	23	-	nC
Q _{gs}	Gate Source Charge		-	4	-	nC
Q _{gd}	Gate Drain ("Miller") Charge		-	3	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{GS} =-10V, V _{DD} =-30V I _D =-4A, R _{GEN} =6Ω	-	7	-	ns
t _r	Turn-On Rise Time		-	5	-	ns
t _{d(off)}	Turn-Off Delay Time		-	65	-	ns
t _f	Turn-Off Fall Time		-	20	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-40	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-320	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =-6A	-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F =-4A, di/dt=100A/us	-	31	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	26	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting T_J=25°C, V_{DD}=30V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=20A
 3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

Test Circuit

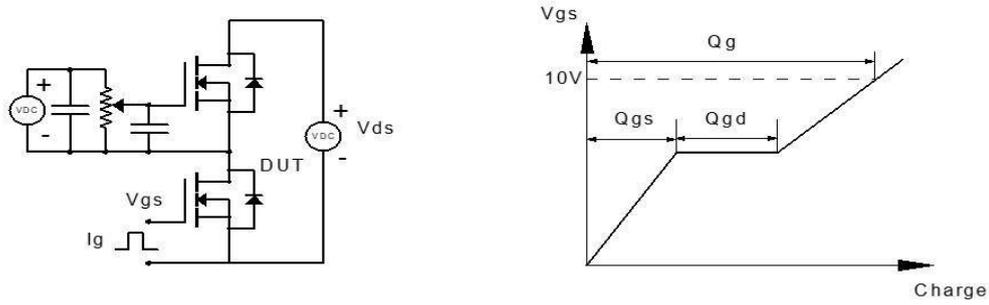


Figure1: Gate Charge Test Circuit & Waveform

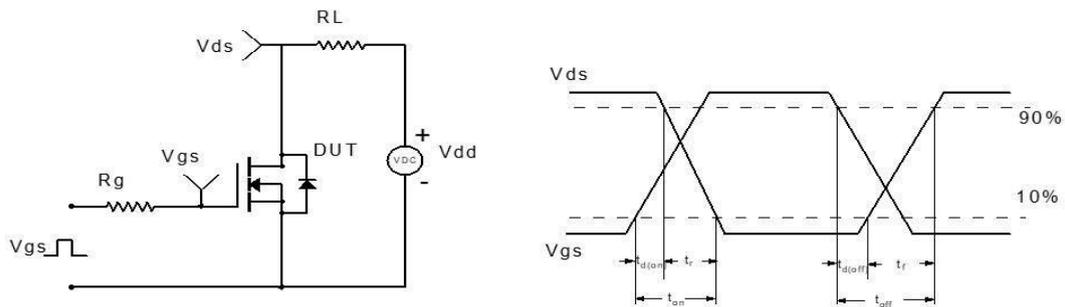


Figure2: Resistive Switching Test Circuit & Waveform

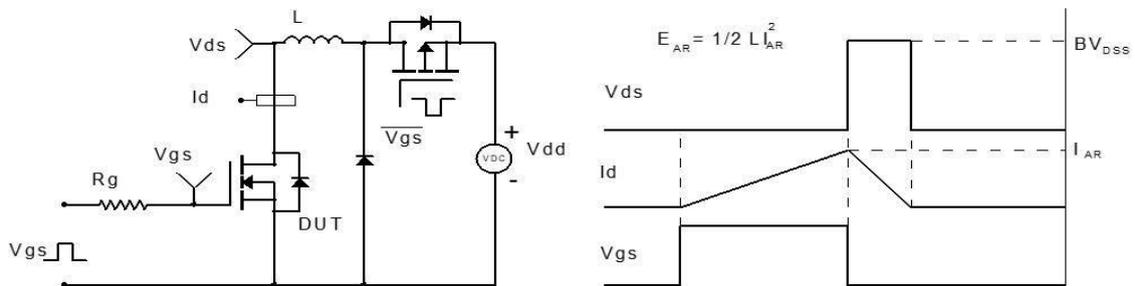


Figure3: Unclamped Inductive Switching Test Circuit & Waveform

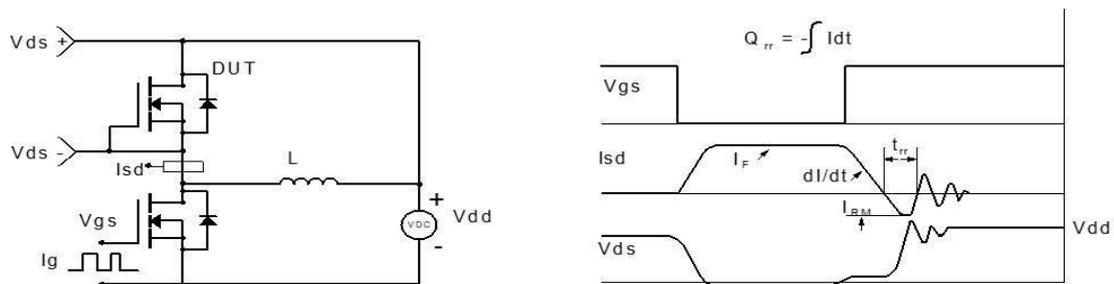
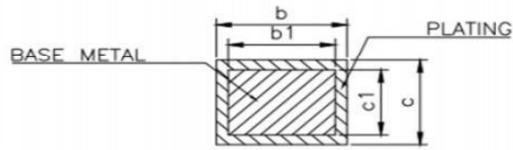
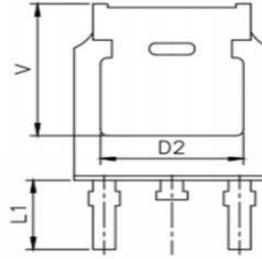
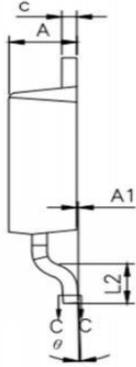
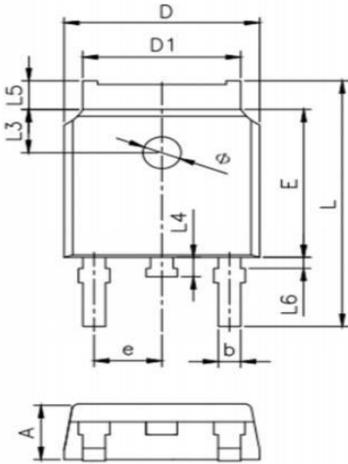


Figure4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-3L)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	--	0.127
b	0.66	--	0.86
b1	0.65	0.76	0.81
D	6.50	6.60	6.70
D1	5.10	5.33	5.46
c	0.47	--	0.60
c1	0.46	0.51	0.56
D2	4.83 REF.		
E	6.00	6.10	6.20
e	2.186	2.286	2.386
L	9.80	10.10	10.40
L1	2.90 REF.		
L2	1.40	1.50	1.60
L3	1.80 REF.		
L4	0.60	0.80	1.00
L5	0.90	--	1.25
L6	0.15	--	0.75
Φ	1.10	--	1.30
θ	0°	--	8°
V	5.40 REF.		